



(51) International Patent Classification:
H01L 33/62 (2010.01) *H01L 33/64* (2010.01)

(21) International Application Number:
PCT/KR2010/001134

(22) International Filing Date:
24 February 2010 (24.02.2010)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
12/381,408 10 March 2009 (10.03.2009) US
12/381,409 10 March 2009 (10.03.2009) US

(71) Applicant (for all designated States except US): **NEPES LED CORPORATION** [KR/KR]; 311-2 Songdae-ri, Ochang-eup, Cheongwon-gun, Chungcheongbuk-Do 363-886 (KR).

(72) Inventor; and

(75) Inventor/Applicant (for US only): **NGUYEN, The Tran** [US/US]; 13642 Barnett Way, Garden Grove, California 92843 (US).

(74) Agent: **Y.P.LEE, MOCK & PARTNERS**; 1575-1, Seocho-dong, Seocho-gu, Seoul 137-875 (KR).

(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM,

AO, AT, AU, AZ, BA, BB, BG, BH, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PE, PG, PH, PL, PT, RO, RS, RU, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

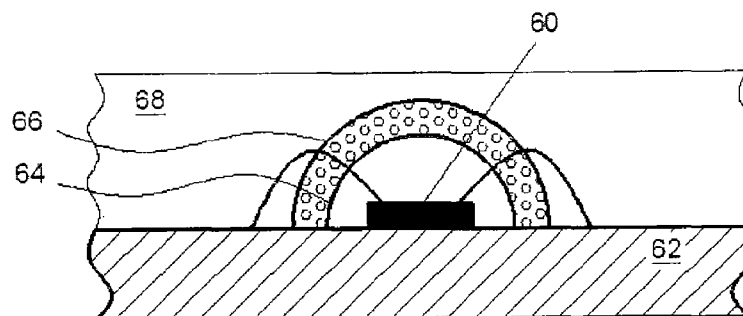
Published:

- with international search report (Art. 21(3))
- before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments (Rule 48.2(h))

(88) Date of publication of the international search report:
25 November 2010

(54) Title: LED LEADFRAME PACKAGE, LED PACKAGE USING THE SAME, AND METHOD OF MANUFACTURING THE LED PACKAGE

[Fig. 1]



(57) Abstract: A LED lead frame package, a LED package using the LED lead frame package, and a method of manufacturing the LED package. In the manufacture of the LED package, a liquid transparent resin material is disposed over at least two ring-shaped protrusions having a sharp upper edge and inclined sidewalls and at least one ring-shaped groove formed between two of the at least two ring-shaped protrusions, and thus a sealing layer having a convex curvature may be easily formed by using surface tension in one process.

